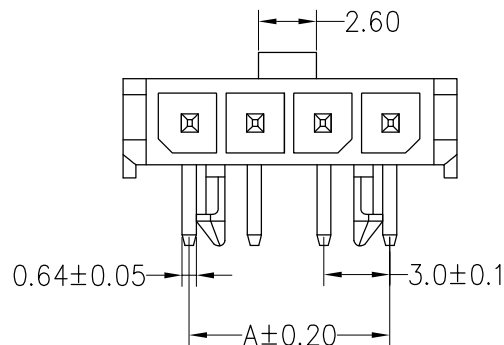


**HSF RoHS**

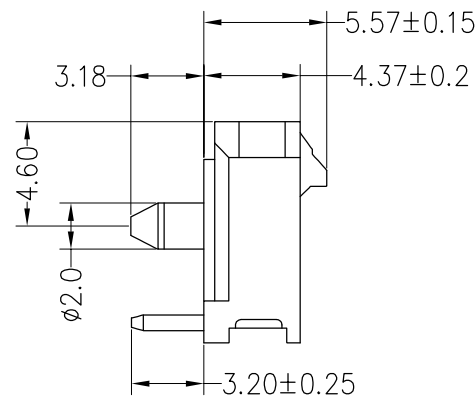
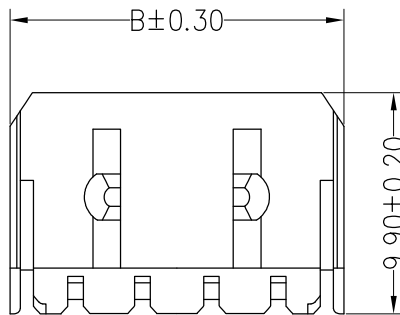
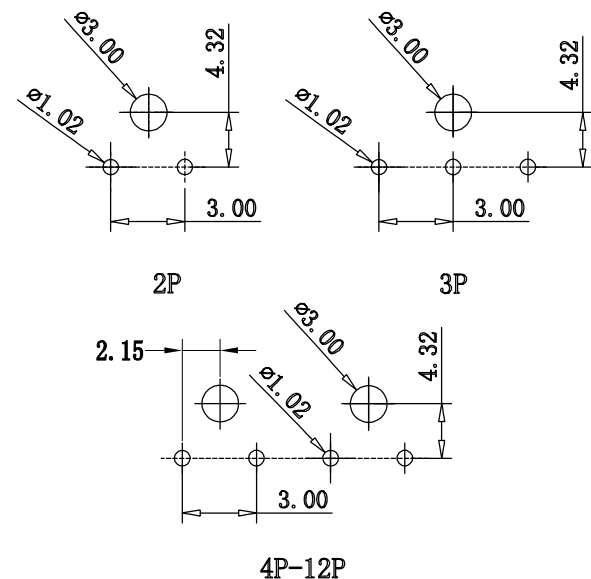
**SPECIFICATIONS**

Rated Current:5.0AMP  
 Voltage rating:250V AC,DC  
 Contact Resistance:20mΩ Max  
 Withstand Voltage:1500V AC/Minute  
 Insulation Resistance:1000MΩ Min  
 Operation Temperature:-40°c to +105°c

Contact Material:Brass  
 Contact Plating:Tin Over Ni  
 Solder Tabs Material:Brass / Tin-plated  
 Insulator Material:Polyester(UL94V-0)  
 Standard: PA6T  
 Max.Processing Temp: 230°C for 30-60 seconds  
 (260°C for 10 seconds)



Recommended P.C.B Layout(Top Side)  
 (PCB BOARD TOLERANCE±0.05)



Circuit	Dimension	
	A	B
02	3.00	9.65
03	6.00	12.65
04	9.00	15.65
05	12.00	18.65
06	15.00	21.65
07	18.00	24.65
08	21.00	27.65
09	24.00	30.65
10	27.00	33.65
11	30.00	36.65
12	33.00	39.65

**Ordering Information**

**JL 3001 R - 1 XX X XX B X 01**

No. of Pins Per Row 2~12P  
 Insulator Material Option C=BK-PA6T E=BK-PA9T F=BK-LCP  
 Contact Plating Option G0:Gold Flash S0:Gold Flash/Tin SN:Tin SM:Matte-Tin  
 Packing Option 0=Pe bag T=Tube R=Reel

				OPERATION		DRAW	YiYuSheng	12.05.22	SCALE	FIT	<b>JILN® 深圳市锦凌电子有限公司</b> <b>SHENZHEN JINLING ELECTRONIC CO.,LTD</b> Tel: 86-755-2997-5806/5802 Fax: 86-755-2997-5992	
				X.X	±0.30							
				X.XX	±0.20	APPROVE	SIZE	A4				
				X.XXX	±0.10		SHEET	1/2				
A0	2012.05.22	NEW DRAWING		Angle	±3°	PART NO.	JL3001R-1XXXXXB01					
REV	DATE	MODIFICATION DESCRIPTION		DIM	TOL		TITLE:	MX3.00mm Wafer 1xNpin 90°				